

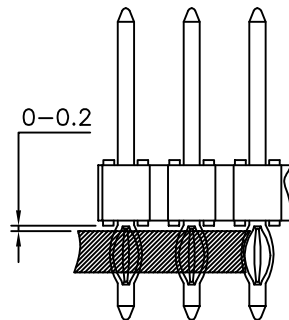
PRODUCT NUMBER
93689-YXX-XXLF

PLATING, SEE TABLE

LEAD FREE
SEE NOTE 6 & 7

TOTAL NB OF POS
02 TO 36

PIN STYLE	DIM "A" REF	DIM "B" ±0.3	DIM "L" REF
01	7.50	4.50	14.78
02	10.14	4.50	17.40
03	5.68	4.50	12.83
04	14.80	4.75	22.15
05	8.30	4.50	15.44
06	6.80	3.60	12.90
07	17.50	3.60	23.85
08	12.20	3.00	17.74
09	9.26	3.20	14.96



RECOMMENDED
POSITION ON THE PCB

DRILLED HOLE $\phi 1.15 \pm 0.025$

Cu $25\mu\text{m}-65\mu\text{m}$

Sn $8\mu\text{m}-18\mu\text{m}$

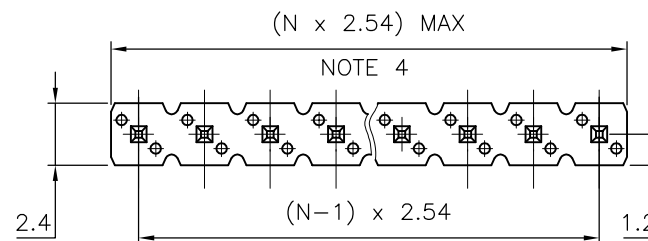
FINISHED PLATED HOLE $\phi 1^{+0.1}_{-0.05}$

$\phi 0.15$

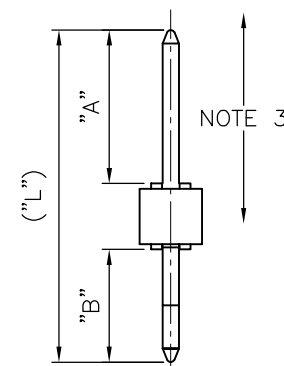
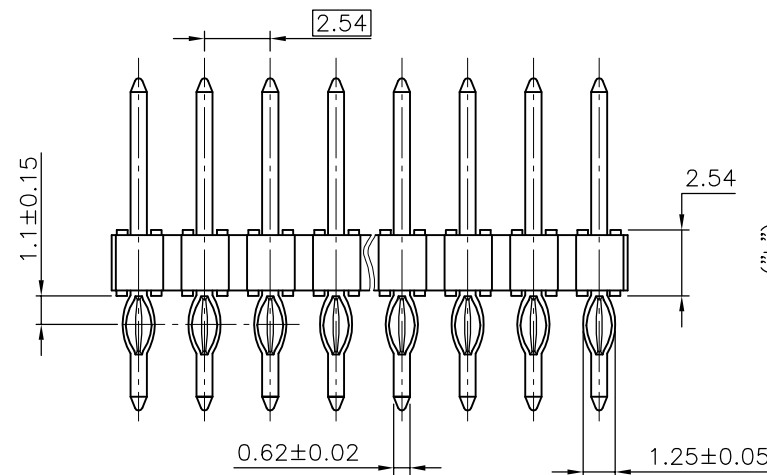
(N x 2.54) MAX

NOTE 4

(N-1) x 2.54



2.54



NOTES:

- 1 - HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
- 2 - PIN MATERIAL : PHOSPHOR BRONZE
- 3 - 9N MIN RETENTION IN EITHER DIRECTION
- 4 - TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS PER ROW, N x 2.54 = 20.32mm
- 5 - STANDARD PACKAGING IN POLYBAGS
- 6 - LEAD FREE CONNECTOR
- 7 - "LF" MEANS THAT THE PRODUCT IS RoHS COMPLIANT THEN MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-47-004

XXXXX-TXXLF	2 μm MIN FULL MATTE TIN PIN TYP PLATED OVER 1.27 μm Ni MIN	
XXXXX-9XXLF	0.2 μm GOLD OVER 1.27 μm Ni MIN	
XXXXX-5XXLF	0.25 μm GOLD/GXT OVER 1.27 μm Ni MIN	1.0 μm TIN OVER 1.27 μm
XXXXX-4XXLF	3.05 μm TIN OVER 1.27 μm Ni MIN	
XXXXX-1XXLF	0.76 μm GOLD/GXT OVER 1.27 μm Ni MIN	1.0 μm TIN OVER 1.27 μm
PLATING NUMBER	CONTACT AREA	PRESS FIT TAIL AREA

mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family BSTIK
ltr	ecn no	dr	date	tolerances unless otherwise specified		 mm scale 5:1	title
R	B-20781	AMA	15.04.28	angles	linear		HEADER P-FIT SINGLE ROW
L	B-16777	JCO	14.01.21	dr	COMPAGNON J	95.07.25	dwg no 93689 type CUSTOMER
M	B-18988	LMU	14.10.06	engr	JMC	95.07.24	
N	B-16427	LMU	14.11.04	chr			
P	B-20744	LMU	15.04.23	appd	JMC	95.07.25	
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